

# ADG706/ADG707—SPECIFICATIONS<sup>1</sup> ( $V_{DD} = 5\text{ V} \pm 10\%$ , $V_{SS} = 0\text{ V}$ , $GND = 0\text{ V}$ , unless otherwise noted.)

Parameter	25°C	-40°C to +85°C	Unit	Test Conditions/Comments
<b>ANALOG SWITCH</b>				
Analog Signal Range		0 V to $V_{DD}$	V	
ON Resistance ( $R_{ON}$ )	2.5 4.5	5	$\Omega$ typ $\Omega$ max	$V_S = 0\text{ V}$ to $V_{DD}$ , $I_{DS} = 10\text{ mA}$ ; Test Circuit 1
ON Resistance Match Between Channels ( $\Delta R_{ON}$ )		0.3 0.8	$\Omega$ typ $\Omega$ max	$V_S = 0\text{ V}$ to $V_{DD}$ , $I_{DS} = 10\text{ mA}$
ON Resistance Flatness ( $R_{FLAT(ON)}$ )	0.5	1.2	$\Omega$ typ $\Omega$ max	$V_S = 0\text{ V}$ to $V_{DD}$ , $I_{DS} = 10\text{ mA}$
<b>LEAKAGE CURRENTS</b>				
Source OFF Leakage $I_S$ (OFF)	$\pm 0.01$ $\pm 0.1$	$\pm 0.3$	nA typ nA max	$V_{DD} = 5.5\text{ V}$ $V_D = 4.5\text{ V}/1\text{ V}$ , $V_S = 1\text{ V}/4.5\text{ V}$ ; Test Circuit 2
Drain OFF Leakage $I_D$ (OFF)	$\pm 0.01$		nA typ	$V_D = 4.5\text{ V}/1\text{ V}$ , $V_S = 1\text{ V}/4.5\text{ V}$ ; Test Circuit 3
ADG706	$\pm 0.4$	$\pm 1.5$	nA max	
ADG707	$\pm 0.2$	$\pm 1$	nA max	
Channel ON Leakage $I_D$ , $I_S$ (ON)	$\pm 0.01$		nA typ	$V_D = V_S = 1\text{ V}$ , or $4.5\text{ V}$ ; Test Circuit 4
ADG706	$\pm 0.4$	$\pm 1.5$	nA max	
ADG707	$\pm 0.2$	$\pm 1$	nA max	
<b>DIGITAL INPUTS</b>				
Input High Voltage, $V_{INH}$		2.4	V min	
Input Low Voltage, $V_{INL}$		0.8	V max	
Input Current				
$I_{INL}$ or $I_{INH}$	0.005	$\pm 0.1$	$\mu\text{A}$ typ $\mu\text{A}$ max	$V_{IN} = V_{INL}$ or $V_{INH}$
$C_{IN}$ , Digital Input Capacitance	5		pF typ	
<b>DYNAMIC CHARACTERISTICS<sup>2</sup></b>				
$t_{TRANSITION}$	40	60	ns typ ns max	$R_L = 300\ \Omega$ , $C_L = 35\text{ pF}$ , Test Circuit 5; $V_{S1} = 3\text{ V}/0\text{ V}$ , $V_{S16} = 0\text{ V}/3\text{ V}$
Break-Before-Make Time Delay, $t_D$	30	1	ns typ ns min	$R_L = 300\ \Omega$ , $C_L = 35\text{ pF}$ ; $V_S = 3\text{ V}$ , Test Circuit 6
$t_{ON}$ (EN)	32	50	ns typ ns max	$R_L = 300\ \Omega$ , $C_L = 35\text{ pF}$ ; $V_S = 3\text{ V}$ , Test Circuit 7
$t_{OFF}$ (EN)	10	14	ns typ ns max	$R_L = 300\ \Omega$ , $C_L = 35\text{ pF}$ ; $V_S = 3\text{ V}$ , Test Circuit 7
Charge Injection	$\pm 5$		pC typ	$V_S = 1\text{ V}$ , $R_S = 0\ \Omega$ , $C_L = 1\text{ nF}$ ; Test Circuit 8
OFF Isolation	-60 -80		dB typ dB typ	$R_L = 50\ \Omega$ , $C_L = 5\text{ pF}$ , $f = 10\text{ MHz}$ ; $R_L = 50\ \Omega$ , $C_L = 5\text{ pF}$ , $f = 1\text{ MHz}$ ; Test Circuit 9
Channel-to-Channel Crosstalk	-60 -80		dB typ dB typ	$R_L = 50\ \Omega$ , $C_L = 5\text{ pF}$ , $f = 10\text{ MHz}$ ; $R_L = 50\ \Omega$ , $C_L = 5\text{ pF}$ , $f = 1\text{ MHz}$ ; Test Circuit 10
-3 dB Bandwidth				
ADG706	25		MHz typ	$R_L = 50\ \Omega$ , $C_L = 5\text{ pF}$ , Test Circuit 9
ADG707	36		MHz typ	$R_L = 50\ \Omega$ , $C_L = 5\text{ pF}$ , Test Circuit 9
$C_S$ (OFF)	13		pF typ	$f = 1\text{ MHz}$
$C_D$ (OFF)				
ADG706	180		pF typ	$f = 1\text{ MHz}$
ADG707	90		pF typ	$f = 1\text{ MHz}$
$C_D$ , $C_S$ (ON)				
ADG706	200		pF typ	$f = 1\text{ MHz}$
ADG707	100		pF typ	$f = 1\text{ MHz}$
<b>POWER REQUIREMENTS</b>				
$I_{DD}$	0.001	1.0	$\mu\text{A}$ typ $\mu\text{A}$ max	$V_{DD} = 5.5\text{ V}$ Digital Inputs = 0 V or 5.5 V

## NOTES

<sup>1</sup>Temperature range is -40°C to +85°C.

<sup>2</sup>Guaranteed by design, not subject to production test.

Specifications subject to change without notice.

# SPECIFICATIONS<sup>1</sup> (V<sub>DD</sub> = 3 V ± 10%, V<sub>SS</sub> = 0 V, GND = 0 V, unless otherwise noted.)

## ADG706/ADG707

Parameter	25°C	-40°C to +85°C	Unit	Test Conditions/Comments
<b>ANALOG SWITCH</b>				
Analog Signal Range		0 V to V <sub>DD</sub>	V	
ON Resistance (R <sub>ON</sub> )	6		Ω typ	V <sub>S</sub> = 0 V to V <sub>DD</sub> , I <sub>DS</sub> = 10 mA;
	11	12	Ω max	Test Circuit 1
ON Resistance Match Between Channels (ΔR <sub>ON</sub> )		0.4	Ω typ	V <sub>S</sub> = 0 V to V <sub>DD</sub> , I <sub>DS</sub> = 10 mA
		1.2	Ω max	
ON Resistance Flatness (R <sub>FLAT(ON)</sub> )		3	Ω typ	V <sub>S</sub> = 0 V to V <sub>DD</sub> , I <sub>DS</sub> = 10 mA
<b>LEAKAGE CURRENTS</b>				
Source OFF Leakage I <sub>S</sub> (OFF)	±0.01		nA typ	V <sub>DD</sub> = 3.3 V
	±0.1	±0.3	nA max	V <sub>S</sub> = 3 V/1 V, V <sub>D</sub> = 1 V/3 V;
Drain OFF Leakage I <sub>D</sub> (OFF)	±0.01		nA typ	Test Circuit 2
ADG706	±0.4	±1.5	nA max	V <sub>S</sub> = 3 V/1 V, V <sub>D</sub> = 1 V/3 V;
ADG707	±0.2	±1	nA max	Test Circuit 3
Channel ON Leakage I <sub>D</sub> , I <sub>S</sub> (ON)	±0.01		nA typ	V <sub>S</sub> = V <sub>D</sub> = 1 V or 3 V;
ADG706	±0.4	±1.5	nA max	Test Circuit 4
ADG707	±0.2	±1	nA max	
<b>DIGITAL INPUTS</b>				
Input High Voltage, V <sub>INH</sub>		2.0	V min	
Input Low Voltage, V <sub>INL</sub>		0.8	V max	
Input Current				
I <sub>INL</sub> or I <sub>INH</sub>	0.005		μA typ	V <sub>IN</sub> = V <sub>INL</sub> or V <sub>INH</sub>
		±0.1	μA max	
C <sub>IN</sub> , Digital Input Capacitance	5		pF typ	
<b>DYNAMIC CHARACTERISTICS<sup>2</sup></b>				
t <sub>TRANSITION</sub>	45		ns typ	R <sub>L</sub> = 300 Ω, C <sub>L</sub> = 35 pF, Test Circuit 5
		75	ns max	V <sub>S1</sub> = 2 V/0 V, V <sub>S16</sub> = 0 V/2 V
Break-Before-Make Time Delay, t <sub>D</sub>	30		ns typ	R <sub>L</sub> = 300 Ω, C <sub>L</sub> = 35 pF;
		1	ns min	V <sub>S</sub> = 2 V, Test Circuit 6
t <sub>ON</sub> (EN)	40		ns typ	R <sub>L</sub> = 300 Ω, C <sub>L</sub> = 35 pF;
		70	ns max	V <sub>S</sub> = 2 V, Test Circuit 7
t <sub>OFF</sub> (EN)	20		ns typ	R <sub>L</sub> = 300 Ω, C <sub>L</sub> = 35 pF;
		28	ns max	V <sub>S</sub> = 2 V, Test Circuit 7
Charge Injection	±5		pC typ	V <sub>S</sub> = 1 V, R <sub>S</sub> = 0 Ω, C <sub>L</sub> = 1 nF;
				Test Circuit 8
OFF Isolation	-60		dB typ	R <sub>L</sub> = 50 Ω, C <sub>L</sub> = 5 pF, f = 10 MHz;
	-80		dB typ	R <sub>L</sub> = 50 Ω, C <sub>L</sub> = 5 pF, f = 1 MHz;
				Test Circuit 9
Channel-to-Channel Crosstalk	-60		dB typ	R <sub>L</sub> = 50 Ω, C <sub>L</sub> = 5 pF, f = 10 MHz;
	-80		dB typ	R <sub>L</sub> = 50 Ω, C <sub>L</sub> = 5 pF, f = 1 MHz;
				Test Circuit 10
-3 dB Bandwidth				
ADG706	25		MHz typ	R <sub>L</sub> = 50 Ω, C <sub>L</sub> = 5 pF, Test Circuit 9
ADG707	36		MHz typ	R <sub>L</sub> = 50 Ω, C <sub>L</sub> = 5 pF, Test Circuit 9
C <sub>S</sub> (OFF)	13		pF typ	f = 1 MHz
C <sub>D</sub> (OFF)				
ADG706	180		pF typ	f = 1 MHz
ADG707	90		pF typ	f = 1 MHz
C <sub>D</sub> , C <sub>S</sub> (ON)				
ADG706	200		pF typ	f = 1 MHz
ADG707	100		pF typ	f = 1 MHz
<b>POWER REQUIREMENTS</b>				
I <sub>DD</sub>	0.001		μA typ	V <sub>DD</sub> = 3.3 V
		1.0	μA max	Digital Inputs = 0 V or 3.3 V

### NOTES

<sup>1</sup>Temperature range is -40°C to +85°C.

<sup>2</sup>Guaranteed by design, not subject to production test.

Specifications subject to change without notice.

# ADG706/ADG707

## DUAL SUPPLY<sup>1</sup> ( $V_{DD} = +2.5\text{ V} \pm 10\%$ , $V_{SS} = -2.5\text{ V} \pm 10\%$ , $GND = 0\text{ V}$ , unless otherwise noted.)

Parameter	25°C	-40°C to +85°C	Unit	Test Conditions/Comments
<b>ANALOG SWITCH</b>				
Analog Signal Range		$V_{SS}$ to $V_{DD}$	V	
ON Resistance ( $R_{ON}$ )	2.5		$\Omega$ typ	$V_S = V_{SS}$ to $V_{DD}$ , $I_{DS} = 10\text{ mA}$ ; Test Circuit 1
	4.5	5	$\Omega$ max	
ON Resistance Match Between Channels ( $\Delta R_{ON}$ )		0.3	$\Omega$ typ	$V_S = V_{SS}$ to $V_{DD}$ , $I_{DS} = 10\text{ mA}$
		0.8	$\Omega$ max	
ON Resistance Flatness ( $R_{FLAT(ON)}$ )	0.5		$\Omega$ typ	$V_S = V_{SS}$ to $V_{DD}$ , $I_{DS} = 10\text{ mA}$
		1.2	$\Omega$ max	
<b>LEAKAGE CURRENTS</b>				
Source OFF Leakage $I_S$ (OFF)	$\pm 0.01$		nA typ	$V_{DD} = +2.75\text{ V}$ , $V_{SS} = -2.75\text{ V}$ $V_S = +2.25\text{ V}/-1.25\text{ V}$ , $V_D = -1.25\text{ V}/+2.25\text{ V}$ ; Test Circuit 2
	$\pm 0.1$	$\pm 0.3$	nA max	
Drain OFF Leakage $I_D$ (OFF)	$\pm 0.01$		nA typ	$V_S = +2.25\text{ V}/-1.25\text{ V}$ , $V_D = -1.25\text{ V}/+2.25\text{ V}$ ; Test Circuit 3
ADG706	$\pm 0.4$	$\pm 1.5$	nA max	
ADG707	$\pm 0.2$	$\pm 1$	nA max	
Channel ON Leakage $I_D$ , $I_S$ (ON)	$\pm 0.01$		nA typ	$V_S = V_D = +2.25\text{ V}/-1.25\text{ V}$ , Test Circuit 4
ADG706	$\pm 0.4$	$\pm 1.5$	nA max	
ADG707	$\pm 0.2$	$\pm 1$	nA max	
<b>DIGITAL INPUTS</b>				
Input High Voltage, $V_{INH}$		1.7	V min	
Input Low Voltage, $V_{INL}$		0.7	V max	
Input Current $I_{INL}$ or $I_{INH}$	0.005		$\mu\text{A}$ typ	$V_{IN} = V_{INL}$ or $V_{INH}$
		$\pm 0.1$	$\mu\text{A}$ max	
$C_{IN}$ , Digital Input Capacitance	5		pF typ	
<b>DYNAMIC CHARACTERISTICS<sup>2</sup></b>				
$t_{TRANSITION}$	40		ns typ	$R_L = 300\ \Omega$ , $C_L = 35\text{ pF}$ , Test Circuit 5
		60	ns max	$V_{S1} = 1.5\text{ V}/0\text{ V}$ , $V_{S16} = 0\text{ V}/1.5\text{ V}$
Break-Before-Make Time Delay, $t_D$	15		ns typ	$R_L = 300\ \Omega$ , $C_L = 35\text{ pF}$ ; $V_S = 1.5\text{ V}$ , Test Circuit 6
		1	ns min	
$t_{ON}$ (EN)	32		ns typ	$R_L = 300\ \Omega$ , $C_L = 35\text{ pF}$ ; $V_S = 1.5\text{ V}$ , Test Circuit 7
		50	ns max	
$t_{OFF}$ (EN)	16		ns typ	$R_L = 300\ \Omega$ , $C_L = 35\text{ pF}$ ; $V_S = 1.5\text{ V}$ , Test Circuit 7
		26	ns max	
Charge Injection	$\pm 8$		pC typ	$V_S = 0\text{ V}$ , $R_S = 0\ \Omega$ , $C_L = 1\text{ nF}$ ; Test Circuit 8
OFF Isolation	-60		dB typ	$R_L = 50\ \Omega$ , $C_L = 5\text{ pF}$ , $f = 10\text{ MHz}$ ; $R_L = 50\ \Omega$ , $C_L = 5\text{ pF}$ , $f = 1\text{ MHz}$ ; Test Circuit 9
	-80		dB typ	
Channel-to-Channel Crosstalk	-60		dB typ	$R_L = 50\ \Omega$ , $C_L = 5\text{ pF}$ , $f = 10\text{ MHz}$ ; $R_L = 50\ \Omega$ , $C_L = 5\text{ pF}$ , $f = 1\text{ MHz}$ ; Test Circuit 10
	-80		dB typ	
-3 dB Bandwidth				
ADG706	25		MHz typ	$R_L = 50\ \Omega$ , $C_L = 5\text{ pF}$ , Test Circuit 9
ADG707	36		MHz typ	$R_L = 50\ \Omega$ , $C_L = 5\text{ pF}$ , Test Circuit 9
$C_S$ (OFF)	13		pF typ	$f = 1\text{ MHz}$
$C_D$ (OFF)				
ADG706	180		pF typ	$f = 1\text{ MHz}$
ADG707	90		pF typ	$f = 1\text{ MHz}$
$C_D$ , $C_S$ (ON)				
ADG706	200		pF typ	$f = 1\text{ MHz}$
ADG707	100		pF typ	$f = 1\text{ MHz}$
<b>POWER REQUIREMENTS</b>				
$I_{DD}$	0.001		$\mu\text{A}$ typ	$V_{DD} = +2.75\text{ V}$
		1.0	$\mu\text{A}$ max	Digital Inputs = 0 V or 2.75 V
$I_{SS}$	0.001		$\mu\text{A}$ typ	$V_{SS} = -2.75\text{ V}$
		1.0	$\mu\text{A}$ max	Digital Inputs = 0 V or 2.75 V

### NOTES

<sup>1</sup>Temperature range is -40°C to +85°C.

<sup>2</sup>Guaranteed by design, not subject to production test.

Specifications subject to change without notice.

## ABSOLUTE MAXIMUM RATINGS<sup>1</sup>

(T<sub>A</sub> = 25°C unless otherwise noted.)

V <sub>DD</sub> to V <sub>SS</sub> .....	7 V
V <sub>DD</sub> to GND .....	-0.3 V to +7 V
V <sub>SS</sub> to GND .....	+0.3 V to -3.5 V
Analog Inputs <sup>2</sup> .....	V <sub>SS</sub> - 0.3 V to V <sub>DD</sub> + 0.3 V or 30 mA, Whichever Occurs First
Digital Inputs <sup>2</sup> .....	-0.3 V to V <sub>DD</sub> + 0.3 V or 30 mA, Whichever Occurs First
Peak Current, S or D .....	100 mA (Pulsed at 1 ms, 10% Duty Cycle max)
Continuous Current, S or D .....	30 mA
Operating Temperature Range	
Industrial .....	-40°C to +85°C

Storage Temperature Range .....	-65°C to +150°C
Junction Temperature .....	150°C
TSSOP Package	
θ <sub>JA</sub> Thermal Impedance .....	97.9°C/W
θ <sub>JC</sub> Thermal Impedance .....	14°C/W
Lead Temperature, Soldering (10 sec) .....	300°C
IR Reflow, Peak Temperature .....	220°C

### NOTES

<sup>1</sup>Stresses above those listed under Absolute Maximum Ratings may cause permanent damage to the device. This is a stress rating only; functional operation of the device at these or any other conditions above those listed in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability. Only one absolute maximum rating may be applied at any one time.

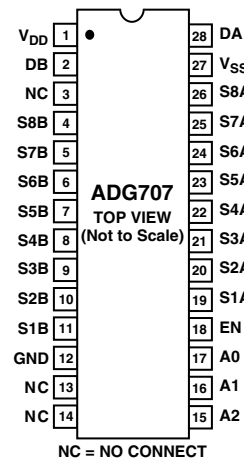
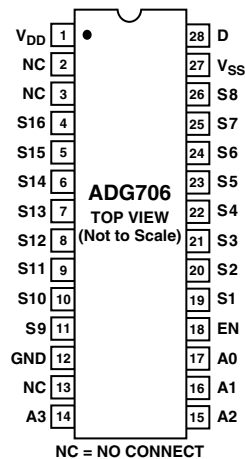
<sup>2</sup>Overtolerances at A, EN, S, or D will be clamped by internal diodes. Current should be limited to the maximum ratings given.

## ORDERING GUIDE

Model <sup>1</sup>	Temperature Range	Package Description	Package Option
ADG706BRU	-40°C to +85°C	28-Lead Thin Shrink Small Outline Package [TSSOP]	RU-28
ADG706BRU-REEL7	-40°C to +85°C	28-Lead Thin Shrink Small Outline Package [TSSOP]	RU-28
ADG706BRUZ	-40°C to +85°C	28-Lead Thin Shrink Small Outline Package [TSSOP]	RU-28
ADG706BRUZ-REEL	-40°C to +85°C	28-Lead Thin Shrink Small Outline Package [TSSOP]	RU-28
ADG706BRUZ-REEL7	-40°C to +85°C	28-Lead Thin Shrink Small Outline Package [TSSOP]	RU-28
ADG707BRU	-40°C to +85°C	28-Lead Thin Shrink Small Outline Package [TSSOP]	RU-28
ADG707BRU-REEL	-40°C to +85°C	28-Lead Thin Shrink Small Outline Package [TSSOP]	RU-28
ADG707BRUZ	-40°C to +85°C	28-Lead Thin Shrink Small Outline Package [TSSOP]	RU-28
ADG707BRUZ-REEL7	-40°C to +85°C	28-Lead Thin Shrink Small Outline Package [TSSOP]	RU-28

<sup>1</sup> Z = RoHS Compliant Part.

## PIN CONFIGURATIONS



### CAUTION

ESD (electrostatic discharge) sensitive device. Electrostatic charges as high as 4000 V readily accumulate on the human body and test equipment and can discharge without detection. Although the ADG706/ADG707 features proprietary ESD protection circuitry, permanent damage may occur on devices subjected to high energy electrostatic discharges. Therefore, proper ESD precautions are recommended to avoid performance degradation or loss of functionality.



# ADG706/ADG707

Table I. ADG706 Truth Table

A3	A2	A1	A0	EN	ON Switch
X	X	X	X	0	NONE
0	0	0	0	1	1
0	0	0	1	1	2
0	0	1	0	1	3
0	0	1	1	1	4
0	1	0	0	1	5
0	1	0	1	1	6
0	1	1	0	1	7
0	1	1	1	1	8
1	0	0	0	1	9
1	0	0	1	1	10
1	0	1	0	1	11
1	0	1	1	1	12
1	1	0	0	1	13
1	1	0	1	1	14
1	1	1	0	1	15
1	1	1	1	1	16

X = Don't Care

Table II. ADG707 Truth Table

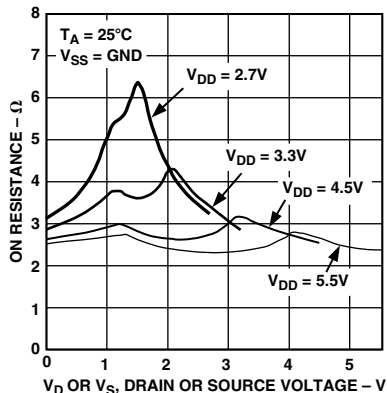
A2	A1	A0	EN	ON Switch Pair
X	X	X	0	NONE
0	0	0	1	1
0	0	1	1	2
0	1	0	1	3
0	1	1	1	4
1	0	0	1	5
1	0	1	1	6
1	1	0	1	7
1	1	1	1	8

X = Don't Care

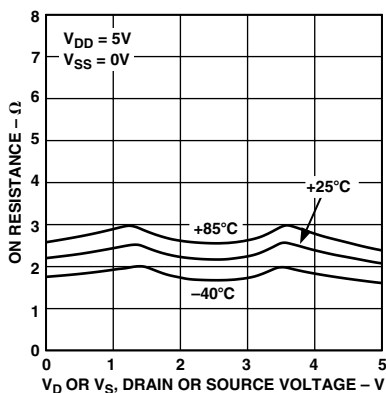
## TERMINOLOGY

$V_{DD}$	Most positive power supply potential	$C_D$ (OFF)	“OFF” Switch drain capacitance. Measured with reference to ground.
$V_{SS}$	Most negative power supply in a dual-supply application. In single-supply applications, this should be tied to ground at the device.	$C_D, C_S$ (ON)	“ON” Switch capacitance. Measured with reference to ground.
$I_{DD}$	Positive supply current	$C_{IN}$	Digital input capacitance
$I_{SS}$	Negative supply current	$t_{TRANSITION}$	Delay time measured between the 50% and 90% points of the digital inputs and the switch “ON” condition when switching from one address state to another
GND	Ground (0 V) reference	$t_{ON}$ (EN)	Delay time between the 50% and 90% points of the EN digital input and the Switch “ON” condition
S	Source terminal. May be an input or output.	$t_{OFF}$ (EN)	Delay time between the 50% and 90% points of the EN digital input and the Switch “OFF” condition
D	Drain terminal. May be an input or output.	$t_{OPEN}$	“OFF” Time measured between the 80% points of both switches when switching from one address state to another
AX	Logic control input	Charge Injection	Measure of the glitch impulse transferred from the digital input to the analog output during switching
EN	Active high device enable	OFF Isolation	Measure of unwanted signal coupling through an “OFF” switch
$V_D$ ( $V_S$ )	Analog voltage on terminals D, S	Crosstalk	Measure of unwanted signal that is coupled through from one channel to another as a result of parasitic capacitance
$R_{ON}$	Ohmic resistance between D and S	Bandwidth	Frequency at which the output is attenuated by 3 dB
$\Delta R_{ON}$	ON Resistance match between any two channels, i.e., $R_{ONmax} - R_{ONmin}$	ON Response	Frequency response of the “ON” Switch
$R_{FLAT(ON)}$	Flatness is defined as the difference between the maximum and minimum value of ON resistance as measured over the specified analog signal range.	Insertion Loss	Loss due to the ON Resistance of the switch
$I_S$ (OFF)	Source leakage current with the Switch “OFF”		
$I_D$ (OFF)	Drain leakage current with the Switch “OFF”		
$I_D, I_S$ (ON)	Channel leakage current with the Switch “ON”		
$V_{INL}$	Maximum input voltage for Logic “0”		
$V_{INH}$	Minimum input voltage for Logic “1”		
$I_{INL}(I_{INH})$	Input current of the digital input		
$C_S$ (OFF)	“OFF” Switch Source Capacitance. Measured with reference to ground.		

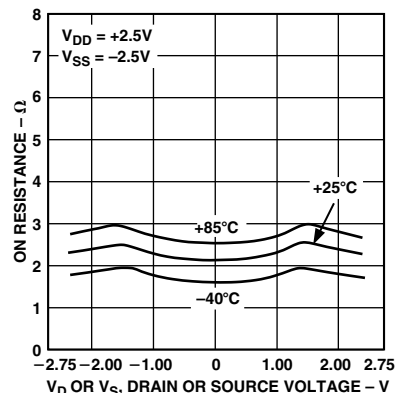
# Typical Performance Characteristics—ADG706/ADG707



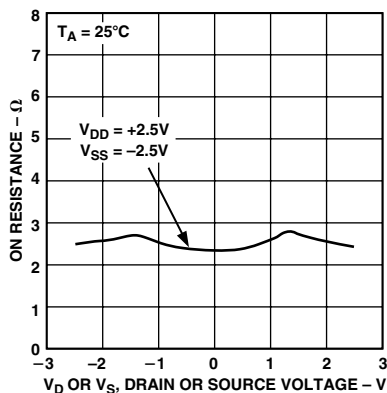
TPC 1. ON Resistance as a Function of  $V_D$  ( $V_S$ ) for Single Supply



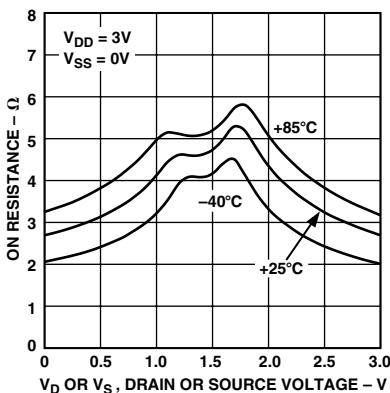
TPC 2. ON Resistance as a Function of  $V_D$  ( $V_S$ ) for Different Temperatures, Single Supply



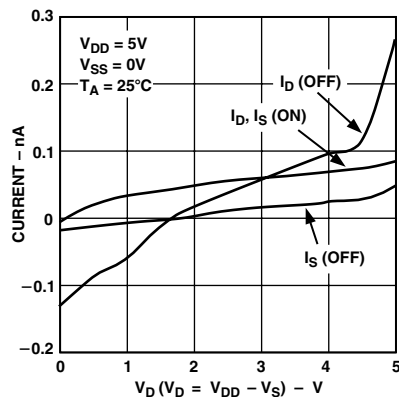
TPC 3. ON Resistance as a Function of  $V_D$  ( $V_S$ ) for Different Temperatures, Dual Supply



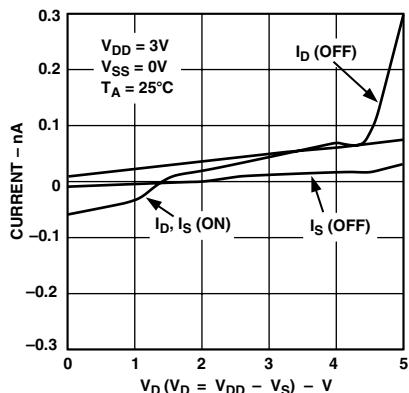
TPC 4. ON Resistance as a Function of  $V_D$  ( $V_S$ ) for Dual Supply



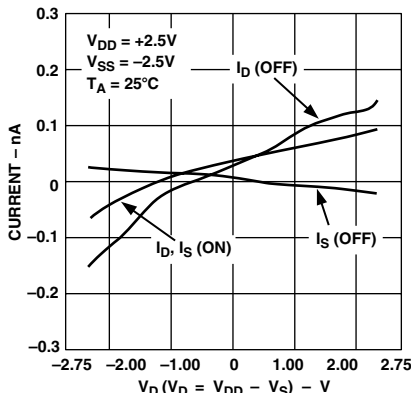
TPC 5. ON Resistance as a Function of  $V_D$  ( $V_S$ ) for Different Temperatures, Single Supply



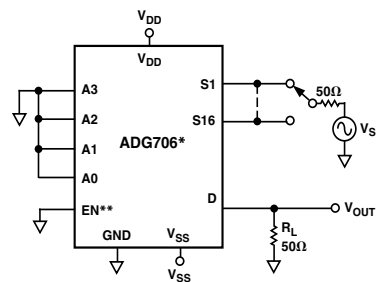
TPC 6. Leakage Currents as a Function of  $V_D$  ( $V_S$ )



TPC 7. Leakage Currents as a Function of  $V_D$  ( $V_S$ )

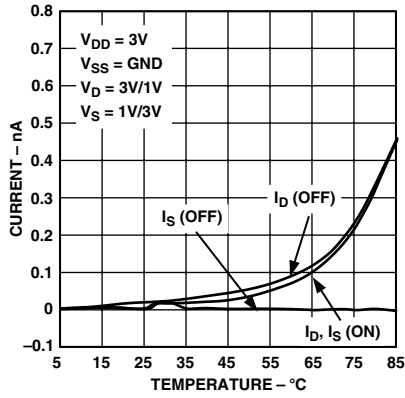


TPC 8. Leakage Currents as a Function of  $V_D$  ( $V_S$ )

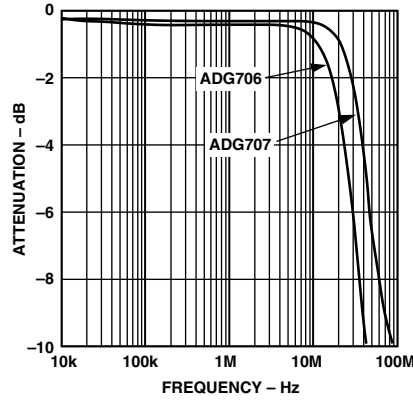


\*SIMILAR CONNECTION FOR ADG707  
 \*\*CONNECT TO 2.4V FOR BANDWIDTH MEASUREMENTS  
 OFF ISOLATION =  $20 \log_{10}(V_{OUT}/V_S)$   
 INSERTION LOSS =  $20 \log_{10} \left( \frac{V_{OUT} \text{ WITH SWITCH}}{V_{OUT} \text{ WITHOUT SWITCH}} \right)$

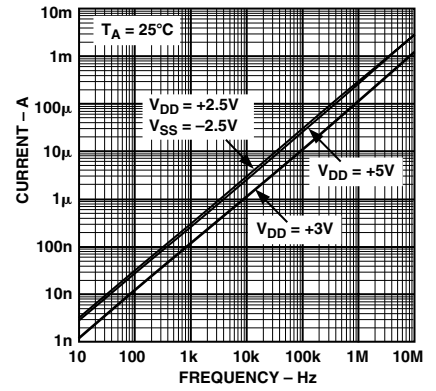
# ADG706/ADG707



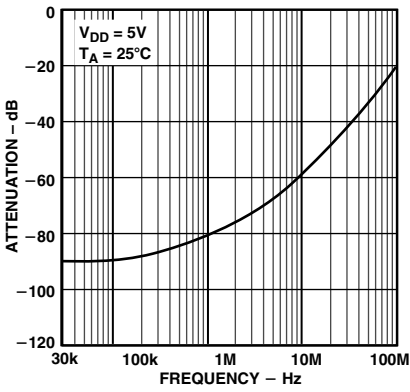
TPC 10. Leakage Currents as a Function of Temperature



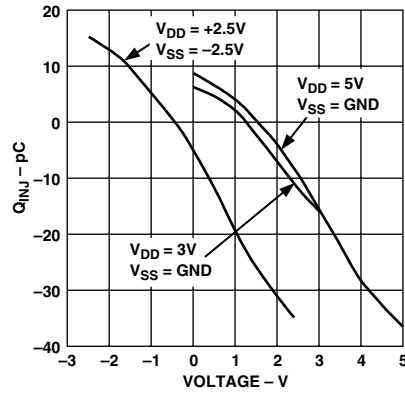
TPC 11. ON Response vs. Frequency



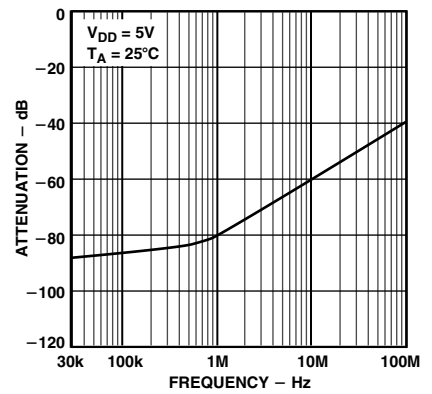
TPC 12. Supply Currents vs. Input Switching Frequency



TPC 13. OFF Isolation vs. Frequency

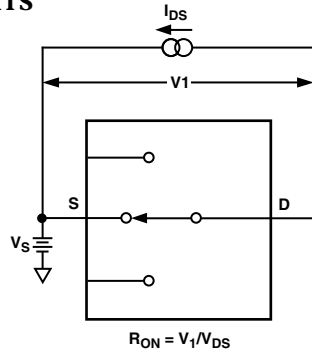


TPC 14. Charge Injection vs. Source Voltage

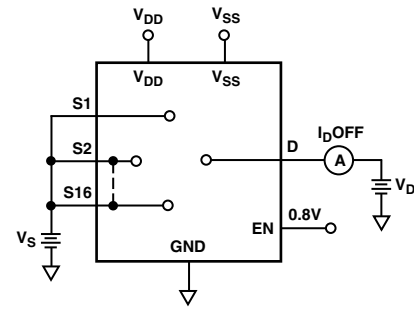


TPC 15. Crosstalk vs. Frequency

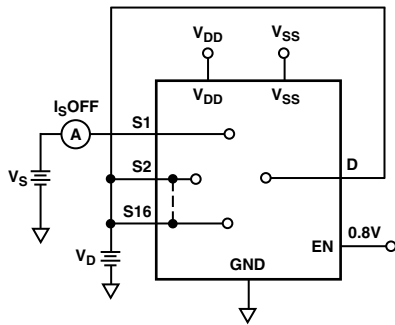
## TEST CIRCUITS



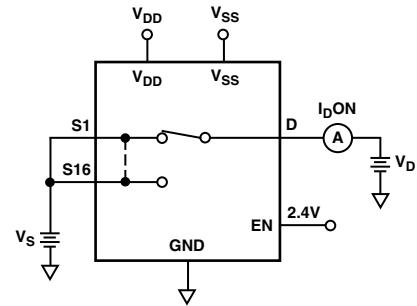
Test Circuit 1. ON Resistance



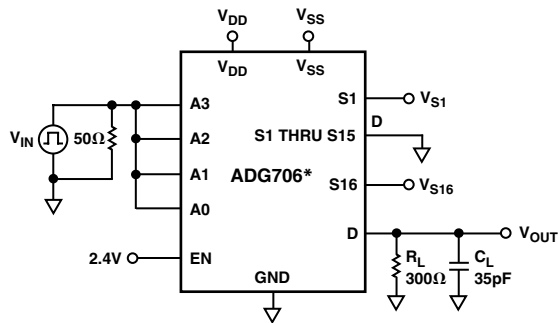
Test Circuit 3.  $I_D$  (OFF)



Test Circuit 2.  $I_S$  (OFF)

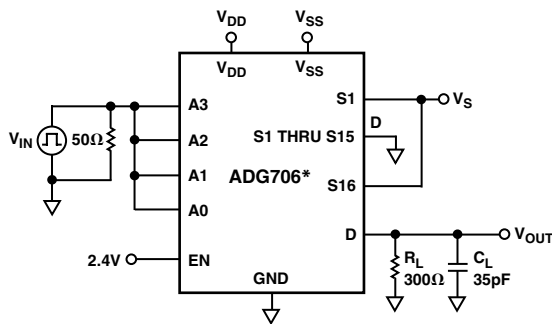
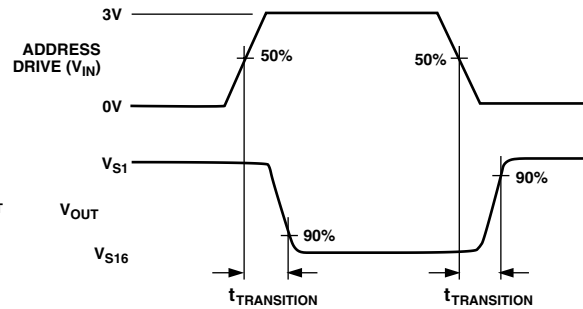


Test Circuit 4.  $I_D$  (ON)



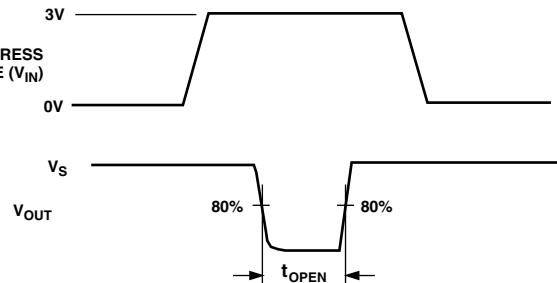
\*SIMILAR CONNECTION FOR ADG707

Test Circuit 5. Switching Time of Multiplexer,  $t_{TRANSITION}$



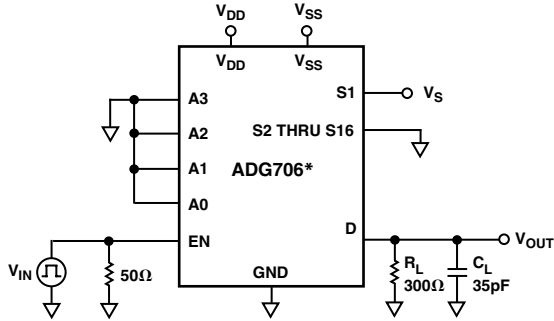
\*SIMILAR CONNECTION FOR ADG707

Test Circuit 6. Break-Before-Make Delay,  $t_{OPEN}$

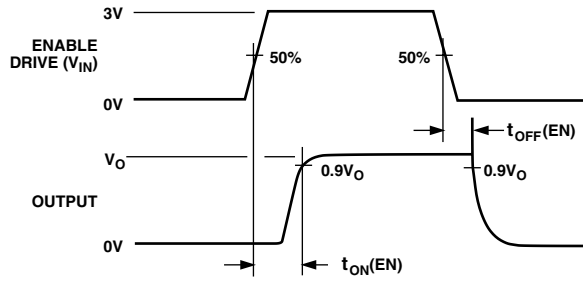




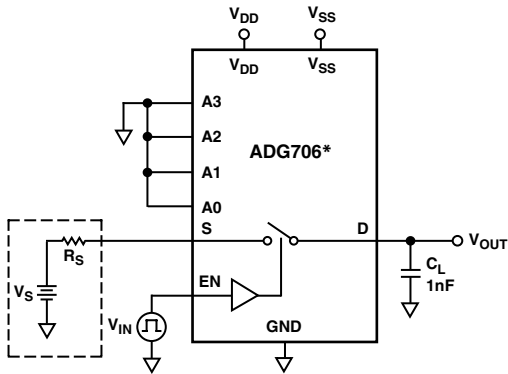
# ADG706/ADG707



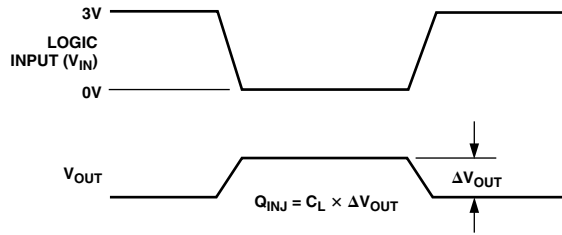
\*SIMILAR CONNECTION FOR ADG707



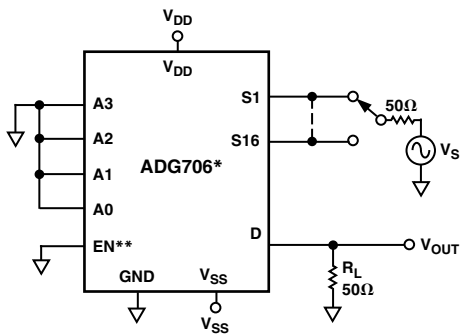
Test Circuit 7. Enable Delay,  $t_{ON}(EN)$ ,  $t_{OFF}(EN)$



\*SIMILAR CONNECTION FOR ADG707



Test Circuit 8. Charge Injection



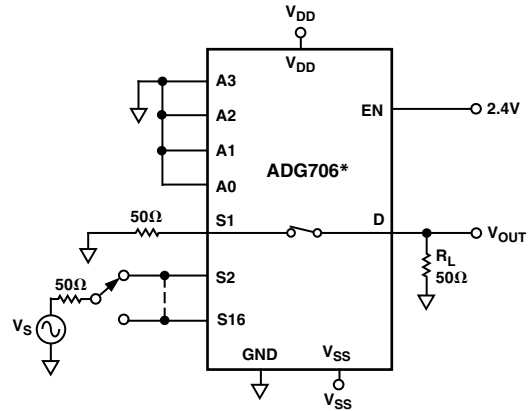
\*SIMILAR CONNECTION FOR ADG707

\*\*CONNECT TO 2.4V FOR BANDWIDTH MEASUREMENTS

OFF ISOLATION =  $20\text{LOG}_{10}(V_{OUT}/V_S)$

INSERTION LOSS =  $20\text{LOG}_{10}\left(\frac{V_{OUT} \text{ WITH SWITCH}}{V_{OUT} \text{ WITHOUT SWITCH}}\right)$

Test Circuit 9. OFF Isolation and Bandwidth

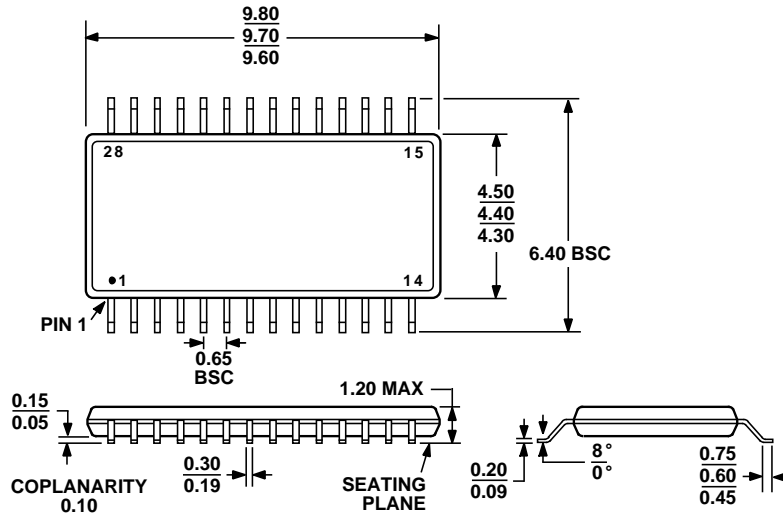


\*SIMILAR CONNECTION FOR ADG707

CHANNEL-TO-CHANNEL CROSSTALK =  $20\text{LOG}_{10}(V_{OUT}/V_S)$

Test Circuit 10. Channel-to-Channel Crosstalk

OUTLINE DIMENSIONS



COMPLIANT TO JEDEC STANDARDS MO-153-AE

28-Lead Thin Shrink Small Outline Package [TSSOP]  
(RU-28)

Dimensions shown in millimeters

# ADG706/ADG707

## Revision History

<b>Location</b>	<b>Page</b>
<b>3/16—Data Sheet changed from REV. A to REV. B.</b>	
Changes to ORDERING GUIDE . . . . .	5
Updated OUTLINE DIMENSIONS . . . . .	11
<b>5/02—Data Sheet changed from REV. 0 to REV. A.</b>	
Edits to FEATURES and PRODUCT HIGHLIGHTS . . . . .	1
Changes to SPECIFICATIONS . . . . .	2
Edits to ABSOLUTE MAXIMUM RATINGS notes . . . . .	5
Edits to TPCs 2, 3, 4, 6–9, 12, 14 . . . . .	7–8
Edits to Test Circuits 9 and 10 . . . . .	10